

REMARKS

Claims 1-11 are pending in the application.

Claims 4-11 were withdrawn from consideration.

Claims 1 and 3 were rejected under 35 U.S.C. §103 as being unpatentable over Ohashi et al. ('345) in view of Matsuo et al. ('714).

Claims 2 and 12 were rejected under 35 U.S.C. §103 over Ohashi in view of Matsuo et al. and further in view of Klebanoff ('652).

The specification has been amended to correct inaccuracies.

Claims 3 and 12 were canceled without prejudice or disclaimer, and Claim 1 has been amended to more clearly define the invention.

Regarding the Ohashi et al. disclosure, this reference does not show or suggest a light source radiating light onto the semiconductor substrate. In fact, Ohashi teaches shading the first major surface of the wafer such that an illuminance of the first major surface of the wafer is 500 lux or less. Applicant's claim 1, as amended, does not read on the Ohashi et al. disclosure.

Matsuo et al. teaches a washing solution of a semiconductor substrate used in a method of washing a semiconductor substrate by immersing the substrate in that solution and irradiating the surface of the semiconductor substrate in the bath with a light consisting essentially of wavelengths in the range of 500-900nm.

The Examiner states, regarding claim 3, the subject matter of which was added in independent claim 1, as amended, that Ohashi discloses the cleaning step performed after a CMP.

However, neither Ohashi et al. nor Matsuo et al. taken singly or in combination suggest a cleaning step performed during or before a CMP process.

In fact, Ohashi et al. suggests a step of post-washing the semiconductor substrate only after the auxiliary polishing stage by making the wafer wet in the pure water bath 150 and subjecting the same to pure water shower cleaning at the post-cleaning portion 160.

In short, the combination of Ohashi et al. with Matsuo would not lead a skilled artisan to the present invention as claimed.

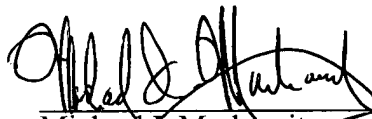
Claim 2 depends on claim 1, as amended.

Klebanoff fails to suggest grounding the semiconductor substrate during the washing step. Furthermore, Klebanoff relates to a chuck which holds a semiconductor substrate and has little to do with the present invention.

In view of the above remarks, it is believed that claims 1 and 2 are in condition for allowance, which action is respectfully solicited. However, if for any reason the Examiner should consider this application not to be in condition for allowance, the Examiner is respectfully requested to telephone the undersigned attorney at the number listed below prior to issuing a further Action.

Any fee due with this paper, not fully covered by an enclosed check, may be charged on Deposit Account 50-1290.

Respectfully submitted,


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